

Sequence Etching and Patterning

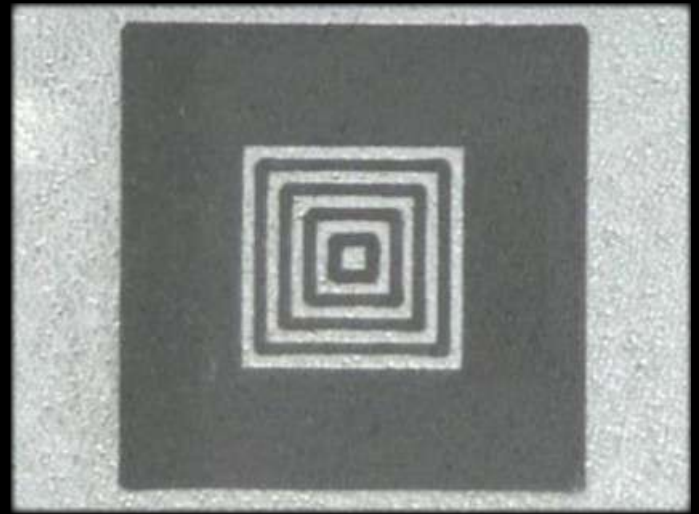
with an Ultra-short Pulse Laser

- Feature1 Possible to suppress the removal depth to the order of several hundred nanometers to several microns
- Feature2 Process various materials (e.g., metals, resins, glass and ceramics)
- Feature3 Possible to remove only the surface layer film without damaging the base material as far as possible

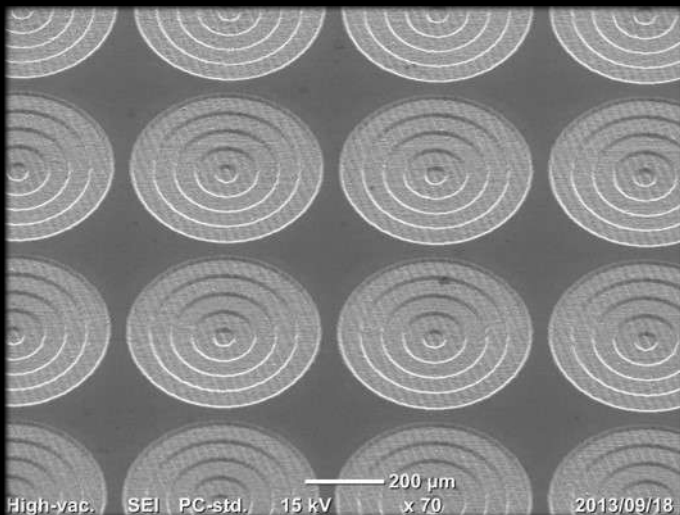
Processing Examples



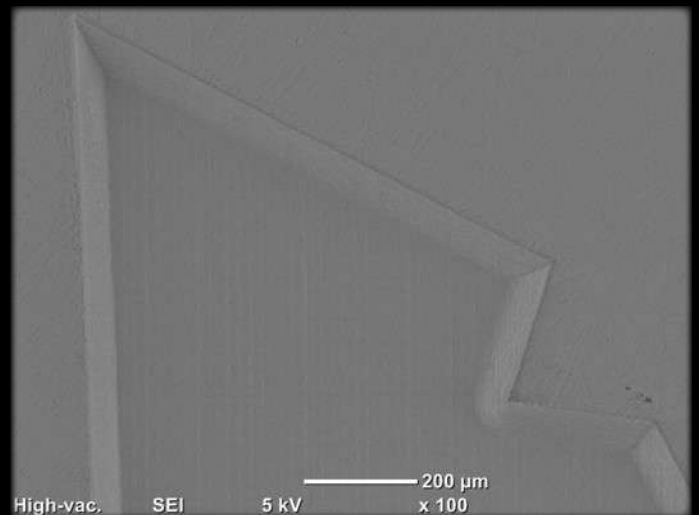
Alumina Ceramic Spot-Facing Processing
Depth: 340 μm / Plate thickness: 380 μm



Aluminum Film Patterning on PET
Film material: Al Plate thickness: 500 \AA L/S: 40 μm / 40 μm



Sequence Etching on Aluminum
Diameter: 50, 150, 250, 350 and 450 μm respectively
Depth: 5 μm for each stage and 25 μm overall



Sequence Etching on Zirconia
Depth: 160 μm



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